

959 Soldering Flux

Low-Solids, No-Clean Liquid Flux

Product Description

Kester 959 soldering Flux is a no-clean, non-corrosive, liquid flux that is designed for the wave soldering of conventional and surface mount circuit board assemblies. 959 was developed to minimize the formation of micro-solder balls during wave soldering operations. This flux contains a small percentage of rosin (1%), which improves solder-ability, heat stability and surface insulation resistance. 959 offers the best wetting and the shiniest solder joints of any no-clean, solvent-based chemistry. It is a very good flux that can be used for secondary soldering such as touch up and repair. 959 leaves evenly distributed residues for the best cosmetic appearance.

Performance Characteristics:

- Minimize micro-solderballs
- Extremely shiny joints
- No streaky, white residues
- Improves soldering performance
- Eliminates the need and expense of cleaning
- Classified as ORL0 per J-STD-004

RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive, 2015/863 for the stated banned substances.

Physical Properties

Specific Gravity: 0.810 ± 0.005

Anton Paar DMA 35 @ 25 °C

Percent Solids (typical): 3.9%

Tested to J-STD-004, IPC-TM-650, Method

Acid Number: 21.8 ± 1.5 mg KOH/g of flux

Tested to J-STD-004, IPC-TM-650, Method 2.3.13

pH (10% solution): 4.6

Hanna Instruments 8314 @ 25 °C

Thinner: 4662

Reliability Properties

Copper Mirror Corrosion: Low

Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Corrosion Test: Low

Tested to J-STD-004B, IPC-TM-650, Method 2.6.15

Silver Chromate: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Chloride and Bromides: None Detected

Tested to J-STD-004, IPC-TM-650, Method 2.3.35

Fluorides by Spot Test: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

Surface Insulation Resistivity (SIR) IPC (typical): Pass

Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

	Blank	959 PD	959 PU
Day 1	$2.7 \times 10^{10} \Omega$	$2.4 \times 10^{10} \Omega$	$2.4 \times 10^{10} \Omega$
Day 4	$1.5 \times 10^{10} \Omega$	$1.5 \times 10^{10} \Omega$	$1.4 \times 10^{10} \Omega$
Day 7	$1.2 \times 10^{10} \Omega$	$1.2 \times 10^{10} \Omega$	$1.1 \times 10^{10} \Omega$

Application

959 can be applied to circuit boards by a spray, foam or dip process. Flux deposition should be 120 to 240 μg of solids/ cm^2 (750 to 1500 μg of solids/ in^2). An air knife after the flux tank is recommended in a foam and wave application to remove excess flux from the circuit board and prevent dripping on the preheated surface.

Process Considerations / Recommendations

The optimum preheat temperature for most circuit assemblies is 90 to 105 °C (194 to 221 °F) as measured on the top or component side of the printed circuit board. Dwell time in the wave is typically 2 to 4 seconds for leaded alloys, and 4 to 8 seconds for lead-free alloys. The conveyor speed should be adjusted to accomplish proper board contact time with the solder. Then the preheat temperatures are adjusted to achieve the required preheat top board temperatures. In the event you need further direction on the setup of your wave soldering system, please contact Kester Technical Support.

Flux Control

Acid number is normally the most reliable method to control the flux concentration of low solids, no clean fluxes. To check concentration, a simple acid-base titration should be used. PS-22 Test Kit and procedure are available from Kester. Control of the flux in the foam flux tank during use is necessary for assurance of consistent flux distribution on the circuit boards. The complex nature of the solvent system for the flux makes it imperative that Kester 4662 Thinner be used to replace evaporative losses. When excessive debris from circuit boards, such as board fibers and from the airline build-up in the flux tank, these particulates will redeposit on the circuit boards which may create a build-up of residues on probe test pins. It is, therefore, necessary to clean the tank and then replenish it with fresh flux when excessive debris accumulates in the flux tank.

Cleaning

959 flux residues are non-conductive, non-corrosive and do not require removal in most applications. If residue removal is required, consult Kester Technical Support for further cleaning recommendation.

Storage, Handling and Shelf Life

959 is flammable. Store away from sources of ignition. Shelf life is 2 years from the date of manufacture when handled properly and held at 10 to 25 °C (50 to 77 °F).

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet and warning label before using this product. Safety Data Sheets are available at <https://www.kester.com/downloads/sds>.

Contact Information

To confirm this document is the most recent version, please contact Assembly@MacDermidAlpha.com

North America 800 West Thorndale Avenue Itasca, IL USA 60143 Phone: +1 800.2.KESTER	Asia Pacific 8/F., Paul Y. Centre 51 Hung To Road Kwun Tong, Kowloon, Hong Kong Phone: +852.3190.3100	Europe Ganghofer Strasse 45 82216 Gerlinden, Germany Phone: +49 (0) 8142 4785 0
---	--	---

Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

DISCLAIMER: All statements, technical information and recommendations contained herein are based on tests we believe to be reliable, but the accuracy or completeness thereof is not guaranteed. No statement or recommendation shall constitute a representation unless set forth in an agreement signed by officers of seller and manufacturer. NO WARRANTY OF MERCHANTABILITY, WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE OR ANY IMPLIED WARRANTY IS MADE. The following warranty is made in lieu of such warranties and all other warranties, express, implied, or statutory. Products are warranted to be free from defects in material and workmanship at the time sold. The sole obligation of seller and manufacturer under this warranty shall be to replace any noncompliant product at the time sold. Under no circumstances shall manufacturer or seller be liable for any loss, damage or expense, direct, indirect, incidental or consequential, arising out of the inability to use the product. Notwithstanding the foregoing, if products are supplied in response to a customer request that specifies operating parameters beyond those stated above, or if products are used under conditions exceeding said parameters, the customer by acceptance or use thereof assumes all risk of product failure and of all direct, indirect, incidental and consequential damages that may result from use of the products under such conditions, and agrees to exonerate, indemnify, defend and hold harmless MacDermid, Incorporated and its affiliates therefrom. No suggestion for product use nor anything contained herein shall be construed as a recommendation to use any product in a manner that infringes any patent or other intellectual property rights, and seller and manufacturer assume no responsibility or liability for any such infringement.

© 2019 MacDermid, Inc. and its group of companies. All rights reserved. "®" and "™" are registered trademarks of MacDermid, Inc. and its group of companies in the United States and/or other countries.